



Material Content Data Sheet



Sales Product Name		ICE3BR1765J		Issued		19. July 2018		
MA#		MA001027120						
Package		PG-DIP-8-13		Weight*		557.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.344	0.60	0.60	6002	6002
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7712	
wire	non noble metal	copper	7440-50-8	174.475	31.31	32.13	313142	321336
	noble metal	gold	7440-57-5	0.274	0.05	0.05	493	493
encapsulation	organic material	carbon black	1333-86-4	1.093	0.20		1963	
	plastics	epoxy resin	-	35.356	6.35		63457	
	inorganic material	silicondioxide	60676-86-0	328.049	58.87	65.42	588773	654193
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13453	13453
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1428	1428
glue	plastics	epoxy resin	-	0.259	0.05		464	
	noble metal	silver	7440-22-4	1.466	0.26	0.31	2631	3095
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com